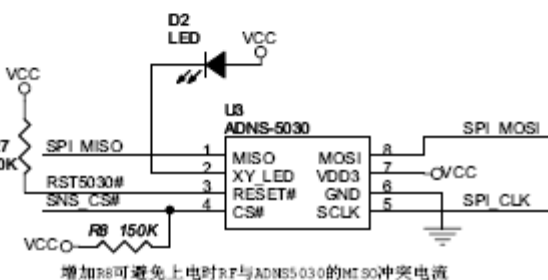
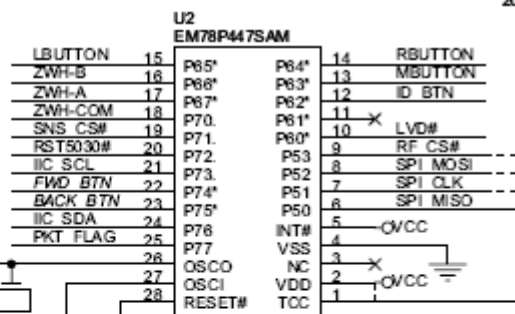
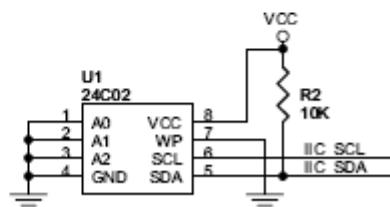
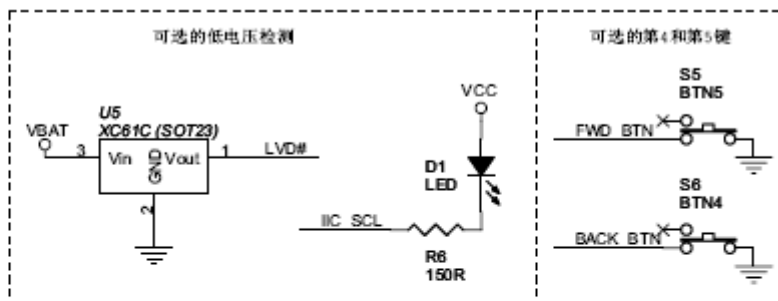
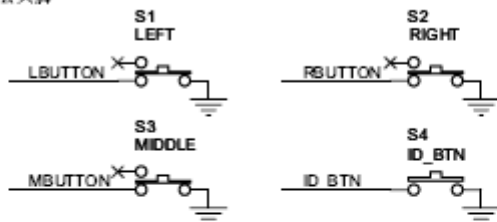
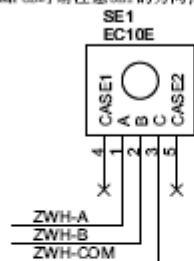
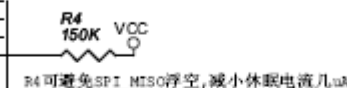


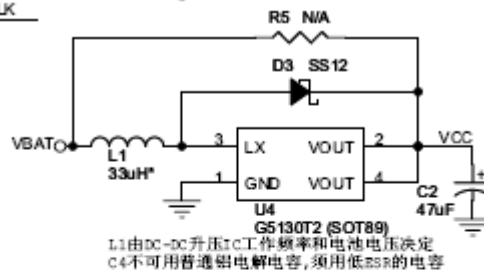
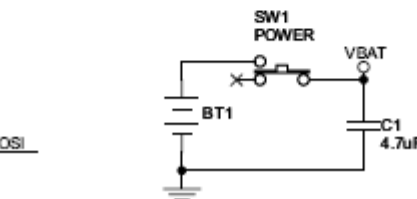
画PCB时请注意SE1的方向, DMB-COM接公共脚



增加R8可避免上电时RF与ADNS5030的MISO冲突电流



R4可避免SPI_MISO浮空,减小休眠电流几uA



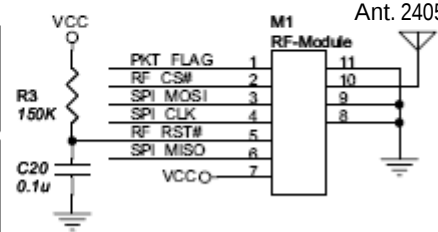
L1由DC-DC升压IC工作频率和电池电压决定
C4不可用普通铝电解电容,须用低ESR的电容

C5的位置请保留,根据电源及开关特性,可能需要焊C3

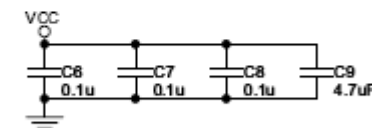
当选用28Pin封装的MCU时, P74~75为第5键和第4键

当选用32Pin封装的MCU时, P74~75为多媒体键的输入
P54~57 (28Pin中无) 为多媒体键的列扫描输出,最多2x4键。

70C连接		Sensor 安装	
VDD	0度	180度	LED Sensor
P51	90度	270度	LED Sensor
P52	180度		
P53	270度		



Ant. 2405~2477MHz



Title